



March 17, 2008

PCN number: 0802

PCN Change Level: Minor

Subject: Process Enhancement for RTAX-S FPGA Products

Dear Customer,

This notice is to inform you that Actel has implemented a refinement in the antifuse etch process for all RTAX-S products manufactured at its United Microelectronics Corporation (UMC) wafer foundry. The change is to improve the antifuse alignment control for improved manufacturability and wafer delivery through tighter process control. This notice affects all RTAX-S devices as listed in Appendix A on page 2.

The process enhancement involves only a minor adjustment during the etching process. Changes remain within the allowable process window of the etching recipe, with no change in the antifuse material, layer thickness, and E-test specification.

The enhancement was first implemented on the RTAX4000S product, which has completed the MIL-STD-883 Class B qualification (see Actel press release on January 28, 2008). The enhanced etching procedure has now been implemented on all versions of the RTAX2000S, RTAX1000S, and RTAX250S products based on this successful qualification of the RTAX4000S.

The RTAX2000S, RTAX1000S, and RTAX250S devices with the enhanced etch process will be phased in as required to meet production requirements, shipping no earlier than July, 2008.

If you have any questions, please contact Actel's Application Technical Support at tech@actel.com.

Regards,
Actel Corporation



Appendix A

Table 1. Devices with Enhanced Etch Process

Actel Device	Package	Speed	Flow	DSCC Part Number
RTAX250S	CQ208, CQ352	Std, -1	B, E, EV, Proto	5962-0421901QYC
				5962-0421902QYC
				5962-0421903QYC
				5962-0421904QYC
				5962-0421901QXC
				5962-0421902QXC
				5962-0421903QXC
				5962-0421904QXC
RTAX1000S	CQ352, CGB624, CGS624, LG624	Std, -1	B, E, EV, Proto	5962-0422001QXC
				5962-0422002QXC
				5962-0422003QXC
				5962-0422004QXC
				5962-0422001QZA
				5962-0422002QZA
				5962-0422003QZA
				5962-0422004QZA
				5962-0422001QUA
				5962-0422002QUA
				5962-0422003QUA
				5962-0422004QUA
				5962-0422001QYC
				5962-0422002QYC
5962-0422003QYC				
5962-0422004QYC				



Table 1. Devices with Enhanced Etch Process

Actel Device	Package	Speed	Flow	DSCC Part Number
RTAX2000S	CQ256, CQ352, CGB624, CGS624, LG624, CG1152, LG1152	Std, -1	B, E, EV, Proto	5962-0422101QUC
				5962-0422102QUC
				5962-0422103QUC
				5962-0422104QUC
				5962-0422101QXC
				5962-0422102QXC
				5962-0422103QXC
				5962-0422104QXC
				5962-0422101QZA
				5962-0422102QZA
				5962-0422103QZA
				5962-0422104QZA
				5962-0422101QNA
				5962-0422102QNA
				5962-0422103QNA
				5962-0422104QNA
				5962-0422101QYC
				5962-0422102QYC
				5962-0422103QYC
				5962-0422104QYC
				5962-0422101QTA
				5962-0422102QTA
				5962-0422103QTA
				5962-0422104QTA
5962-0422101QMC				
5962-0422102QMC				
5962-0422103QMC				
5962-0422104QMC				



Table 1. Devices with Enhanced Etch Process

Actel Device	Package	Speed	Flow	DSCC Part Number
RTAX4000S	CQ352, CG1272, LG1272	Std	B, E, EV, Proto	Not Applicable
RTAX250SL	CQ208, CQ352	Std, -1	B, E, EV	Not Applicable
RTAX1000SL	CQ352, CGB624, CGS624, LG624	Std, -1	B, E, EV	Not Applicable
RTAX2000SL	CQ256, CQ352, CGB624, CGS624, LG624, CG1152, LG1152	Std, -1	B, E, EV	Not Applicable